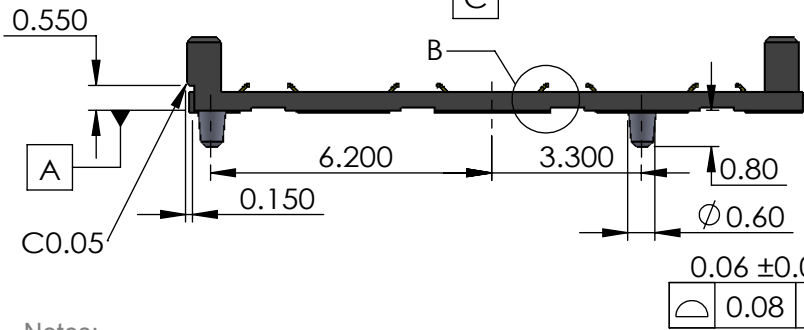
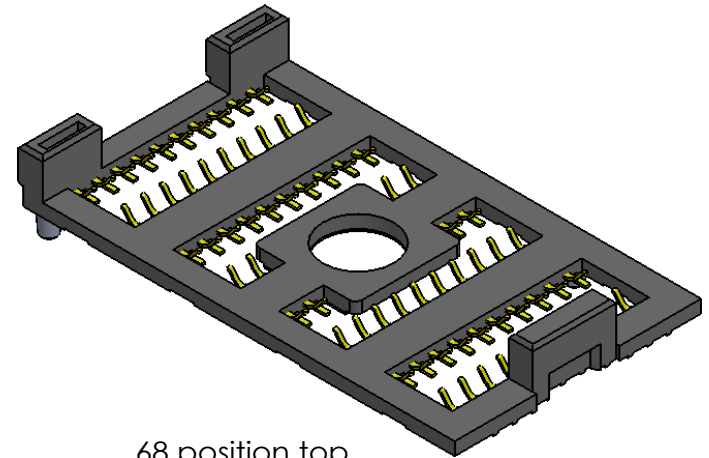
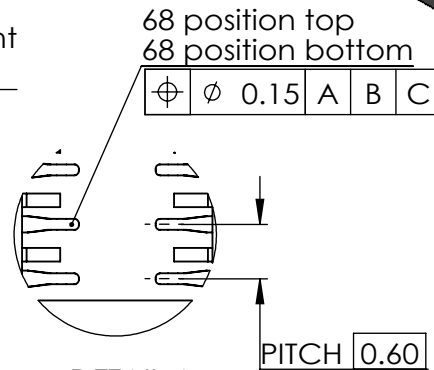


| Revisions | | | |
|-----------|-----------|---|------------|
| REV | ECN # | Description | Date |
| B | R20160015 | 1.Change soldertail height 0.02mm to 0.06mm; 2.Total stack height changed to 1.08mm; 3.Correct FPC pad position & enlarge pad size to 0.4x0.7mm; 4.Enlarge PCB solder pad size to 0.35x0.8mm. | 05/09-2016 |
| C | R20160021 | 1.Define FPC solder mask opening size; 2. Add the post; 3. Change flange height tolerance; 4.Optimize housing size; 5. Remove stiffener fillister . | 06/24-2016 |
| D | R20170002 | Modified post height. | 03/08-2017 |



DETAIL B
SCALE 12 : 1



DETAIL A
SCALE 12 : 1

PITCH 0.60
NCX PN XBM-D068A

Notes:

- Material:
Contacts: High performance copper alloy.
Housing: LCP resin, Glass fiber filled, UL94V-0 rated, black color.
Plating: 5 u" min gold plated on contact tip, gold flash on soldertail area, 70 ± 30 u" nickel underplated.
- This product compliants with European Union directives of RoHS requirements.
- The product can withstand exposure peak temperature 260C for 10 sec in SMT soldering process.
- Recommended stencil thickness no thinner than 0.1mm, solder past opening no less than pad size.

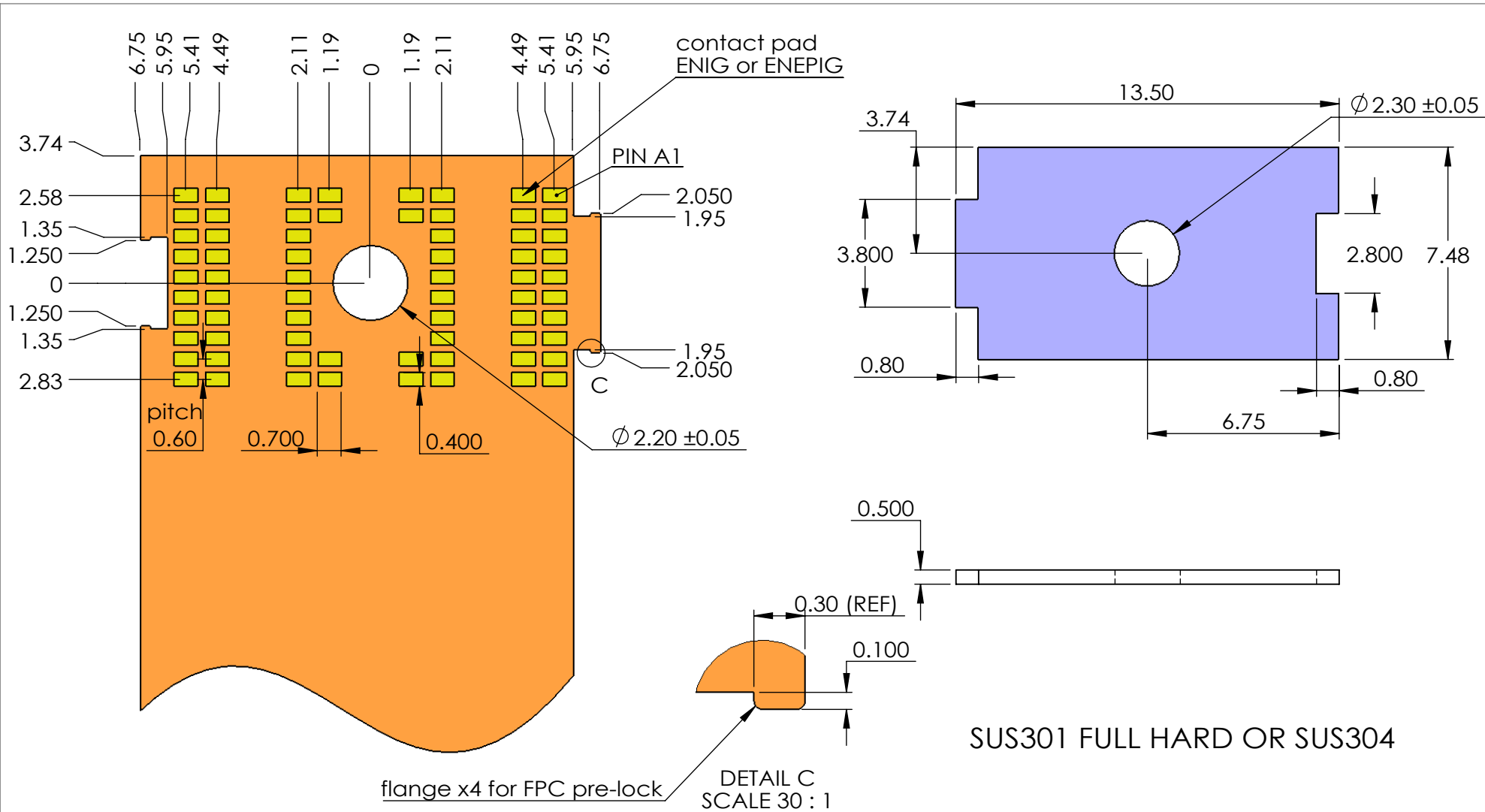
DIMENSIONS ARE IN mm
TOLERANCES (unless otherwise specified):

ANGULAR: ± 2 degree
LINEAR: .X ±0.15
.XX ±0.08
.XXX ±0.04

| | |
|----------|------------|
| MATERIAL | See note 1 |
| FINISH | gold |

| | NAME | DATE |
|---------------|----------------------|------------|
| DRAWN | Huangwei | 05/09-2016 |
| CHECKED | Jason Wu | 05/09-2016 |
| Appr | Gary Hsieh | 05/09-2016 |
| Release level | Preliminary | |
| COMMENTS: | DO NOT SCALE DRAWING | |

| | |
|--|---------|
| 聯能科技 Unimicron Group | |
| Title: 68 pos X-Beam interposer (0.6 mm pitch, M2.0 screw) | |
| projection | SIZE A |
| SCALE:5:1 | WEIGHT: |
| DWG. NO. XBGUAW001 | REV. D |
| SHEET 1 OF 5 | |



Recommend FPC footprint

Note:

1. The stiffener is to align with connector housing when final assembly.
2. The alignment tolerance for FPC & stiffener is $\pm 0.075\text{mm}$.
Based on left notch (1.250+1.250)&right protrusion (2.050+2.050) feature.
3. Solder mask opening min: 0.50 x 0.80 mm min.

Recommend FPC stiffener

DIMENSIONS ARE IN mm
TOLERANCES (unless otherwise specified):

ANGULAR: ± 2 degree
LINEAR: .X ± 0.15
.XX ± 0.08
.XXX ± 0.04

聯能科技 Unimicron Group

Title:
68 pos X-Beam interposer
(0.6 mm pitch, M2.0 screw)

SIZE

A

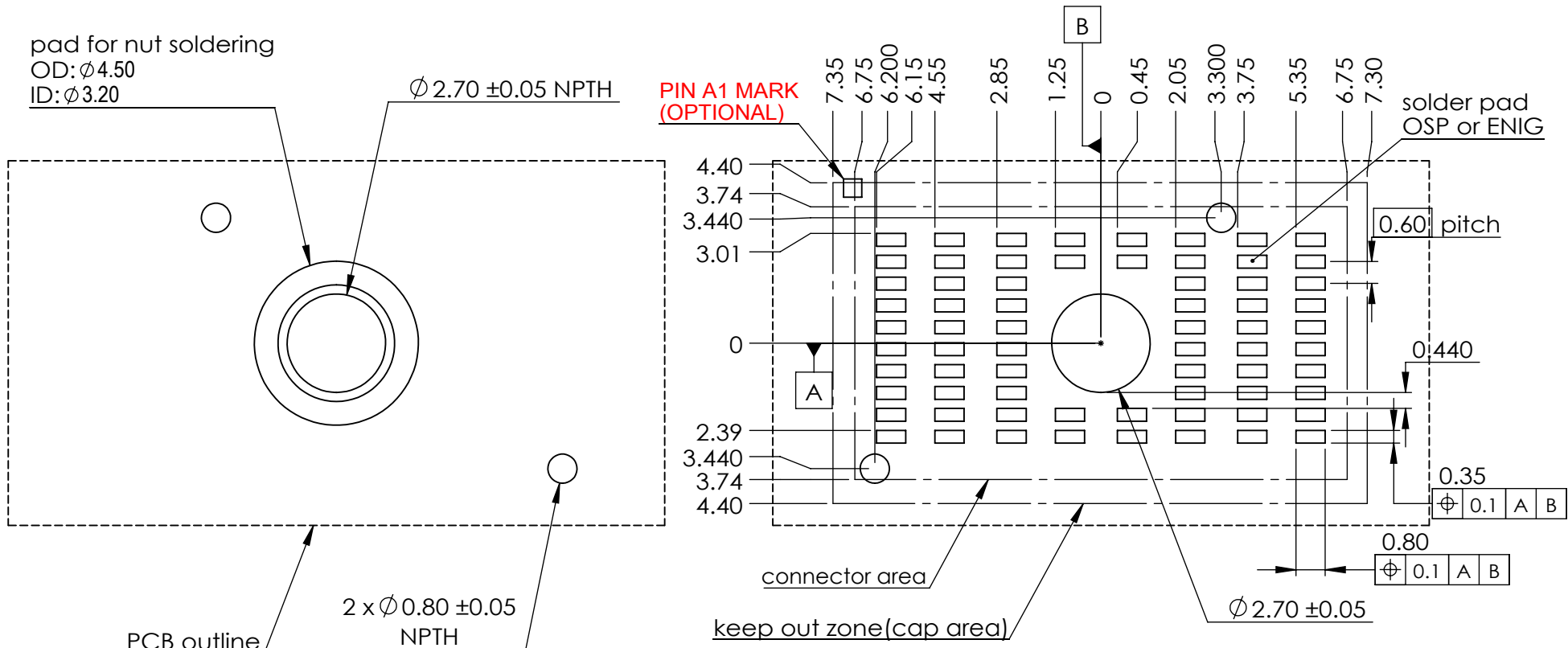
DWG. NO. XBGUAW001

REV.
D

SCALE:5:1

WEIGHT:

SHEET 2 OF 5



Max S/M THK 35um above pad surface

Back side

Front side

Recommend PCB footprint

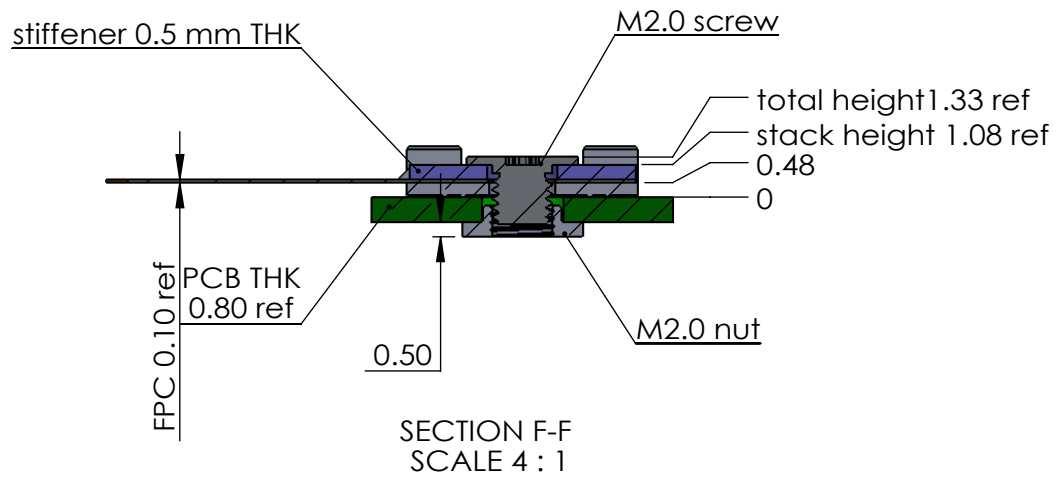
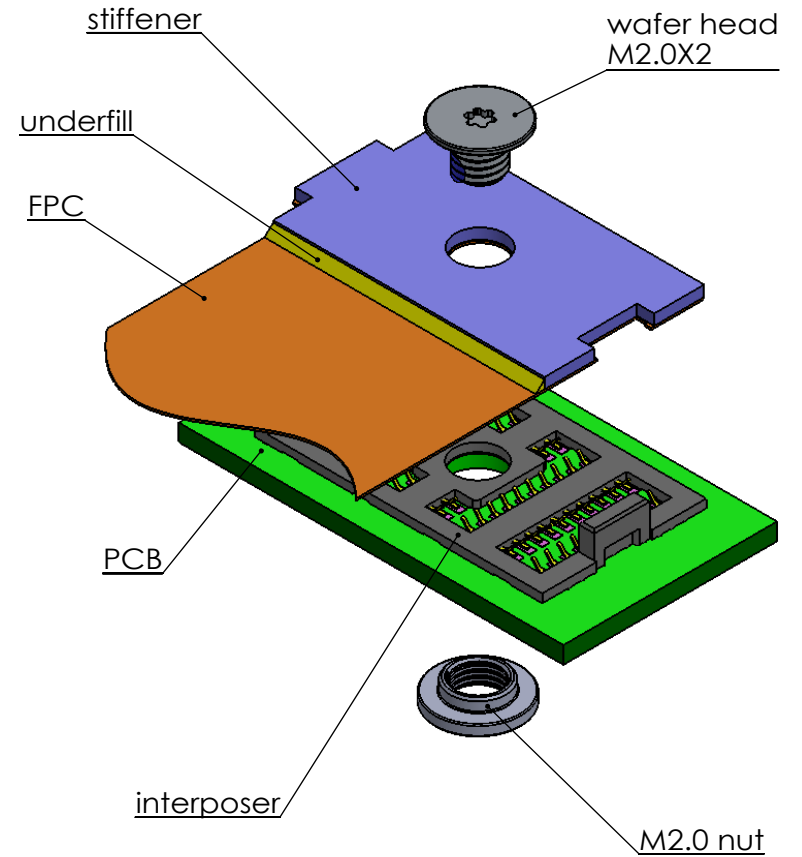
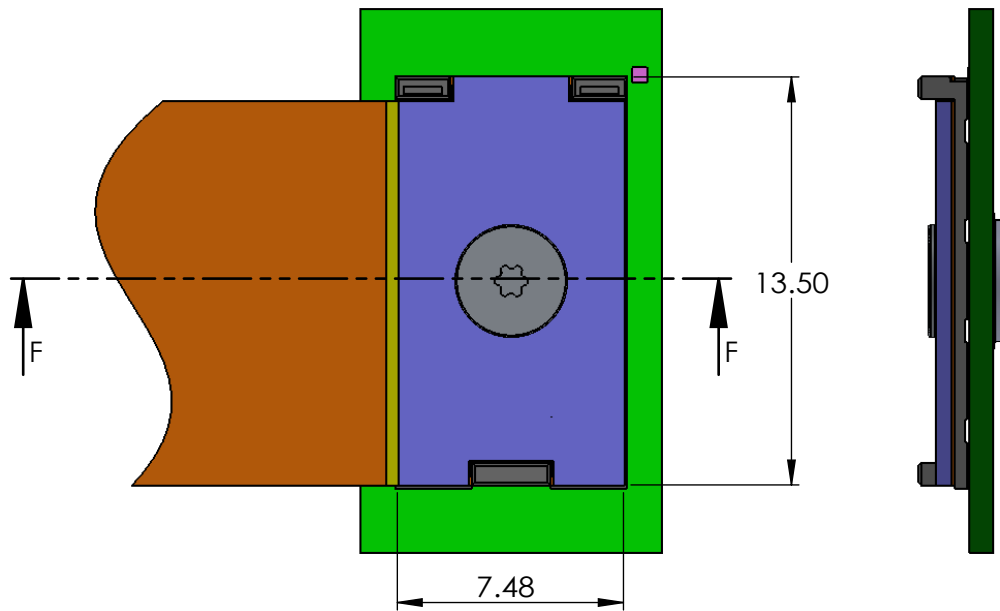
DIMENSIONS ARE IN mm
 TOLERANCES (unless otherwise specified):

ANGULAR: ± 2 degree
 LINEAR: .X ± 0.15
 .XX ± 0.08
 .XXX ± 0.04

聯能科技 Unimicron Group

Title:
 68 pos X-Beam interposer
 (0.6 mm pitch, M2.0 screw)

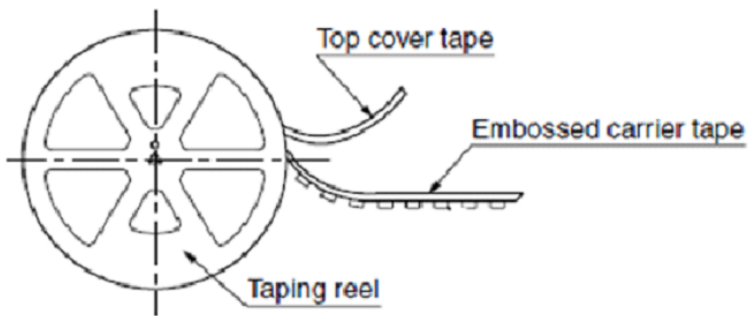
| | | |
|---------------|--------------------|--------------|
| SIZE A | DWG. NO. XBGUAW001 | REV. D |
| SCALE:5:1 | WEIGHT: | SHEET 3 OF 5 |



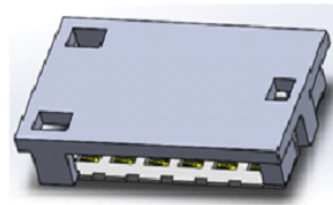
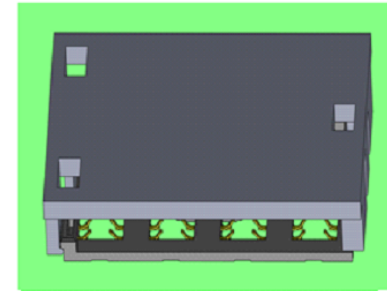
聯能科技 Unimicron Group

Title:
68 pos X-Beam interposer
(0.6 mm pitch, M2.0 screw)

| | | | | | |
|-----------|---|----------|-----------|--------------|---|
| SIZE | A | DWG. NO. | XBGUAW001 | REV. | D |
| SCALE:5:1 | | WEIGHT: | | SHEET 4 OF 5 | |

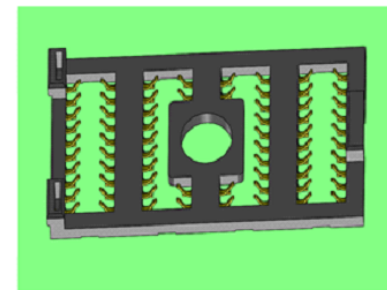


SMT



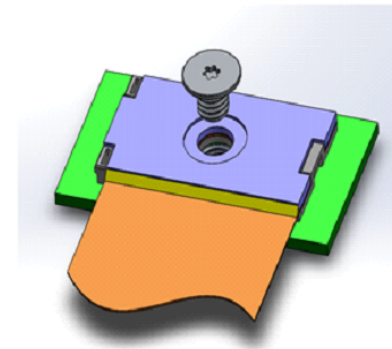
Connector with cap

Remove cap
before FPC
assy



- Tape & reel or tray package for auto-SMT process on board.

Place FPC &
screw lock



package and assembly process

聯能科技 Unimicron Group

Title:
68 pos X-Beam interposer
(0.6 mm pitch, M2.0 screw)

| | | | | | |
|-----------|---|----------|-----------|--------------|---|
| SIZE | A | DWG. NO. | XBGUAW001 | REV. | D |
| SCALE:5:1 | | WEIGHT: | | SHEET 5 OF 5 | |